IN THE SPECIFICATION

Please amend the specification as set forth below.

On Page 5, the paragraph beginning with "Figs. 5", please amend as follows:

Figs. ~~5 is a~~ 5A and 5B are sectional ~~view~~ views showing an application portion of a silicone adhesive according to the present invention;

On Page 5, the paragraph beginning with "Figs. 12A", please amend as follows:

Figs. ~~12A and 12B~~ 12A-12C are sectional views showing a module incorporating a plate-shaped structure according to the present invention;

On Pages 15 and 16, the paragraph beginning with "Fig. 5", please amend as follows:

~~Fig. 5 shows~~ Figs. 5A-5B show a third embodiment of the present invention. In this embodiment, in the situation where corrosive gases diffusively enter from the silicone adhesive 50 as in the cases of the first and second embodiments, the silicone adhesive 50 is used by mixing therein silver, copper,

a silver alloy, or copper alloy subdivided into minute particles, foils, or needles. This method has an advantage that much of the corrosive gases can be trapped into the layer of silicone adhesive 50 before corrosive gases have completely entered the inside the electronics circuitry. That is, the corrosive gasses can be trapped at places more upstream in their diffusion path, thereby producing a significant effect. The electronic apparatus according to this embodiment is configured so that the surface area of the place used for reaction is sufficiently secured to trap a large amount of corrosive gases, by subdividing silver, copper, a silver alloy, or copper alloy into a shape such as not to obstruct the application of the silicone adhesive when mixed therein, such as minute particles, foils, or needles, and by mixing this in a large amount into the silicone adhesive.

On Pages 19 and 20, the paragraph beginning with "Figs. 12A and 12B", please amend as follows:

Figs. ~~12A and 12B~~ 12A-12C are schematic sectional views each showing an embodiment of a structure to which a plate-shaped structure 120 is added, the plate-shaped structure 120

having the conductive material 1 that is applied to the surface thereof in the form of a layer, and that has corrosiveness equal to or higher than that of the materials constituting the electronics circuitry. As for the shape of the plate-shaped structure 1, for example, a bending portion is provided at each of the opposite ends of the plate-shaped structure 120, and the plate-shaped structure 120 is placed over the electronics circuitry 30 after its size has been adjusted to such an extent just as to cover the electronics circuitry (see Fig. 12A). Alternatively, the plate-shaped structure 120 is placed under the electronic circuit board 30 (see Fig. 12B), and the bending portions thereof are caused to rise, thereby forming a structure for protecting the board from corrosive gases. The enlarged view of the portion D in ~~Fig. 12B~~ Fig. 12C shows that the conductive material 1 having corrosiveness equal to or higher than that of the materials constituting the electronics circuitry is formed into a film shape, over the surface of the plate-shaped structure 120. However, depending on the shape of the plate-shaped structure 120, the forming place of the conductive material 1 may be virtually determined based on the capability of trapping corrosive gases, in a way such as the entire periphery or only one portion of the plate-shaped structure 12.